



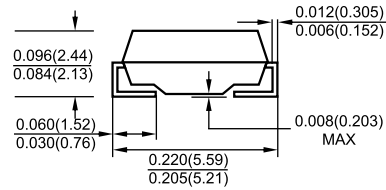
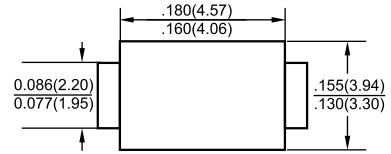
SMB/DO-214AA

Features

- ✧ For surface mounted application
- ✧ Glass passivated junction chip
- ✧ Built-in strain relief, ideal for automated placement
- ✧ Plastic material used carries Underwriters Laboratory Classification 94V-0
- ✧ Fast switching for high efficiency
- ✧ High temperature soldering: 260 °C / 10 seconds at terminals

Mechanical Data

- ✧ Cases: Molded plastic
- ✧ Terminals: Pure tin plated, Lead free.
- ✧ Polarity: Indicated by cathode band
- ✧ Packing: 12mm tape
- ✧ Weight: 0.093 gram



Dimensions in inches and (millimeters)

Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	RS 2A	RS 2B	RS 2D	RS 2G	RS 2J	RS 2K	RS 2M	Units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current See Fig. 1 @ $T_A=100^{\circ}\text{C}$	$I_{(AV)}$	2.0							A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I_{FSM}	50							A
Maximum Instantaneous Forward Voltage @ 2.0A	V_F	1.3							V
Maximum DC Reverse Current @ $T_A=25^{\circ}\text{C}$ at Rated DC Blocking Voltage @ $T_A=125^{\circ}\text{C}$	I_R	5 200							μA μA
Maximum Reverse Recovery Time (Note 1)	T_{rr}	150				250	500		nS
Typical Junction Capacitance (Note 2)	C_j	50							pF
Typical Thermal Resistance (Note 3)	$R_{\theta JA}$ $R_{\theta JL}$	55 18							$^{\circ}\text{C} / \text{W}$
Operating Temperature Range	T_J	-55 to +150							$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150							$^{\circ}\text{C}$

- Notes:
1. Reverse Recovery Test Conditions: $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$
 2. Measured at 1 MHz and Applied $V_R=4.0$ Volts
 3. Thermal Resistance from Junction to Ambient and Junction to Lead Mounted on P.C.B. with 0.4" x 0.4" (10mm x 10 mm) Copper Pad Areas.

RATINGS AND CHARACTERISTIC CURVES (RS2A THRU RS2M)

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

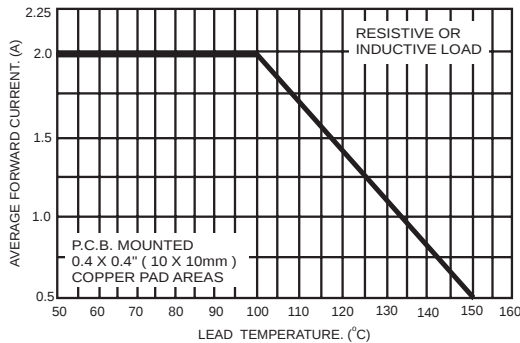


FIG.2- TYPICAL REVERSE CHARACTERISTICS

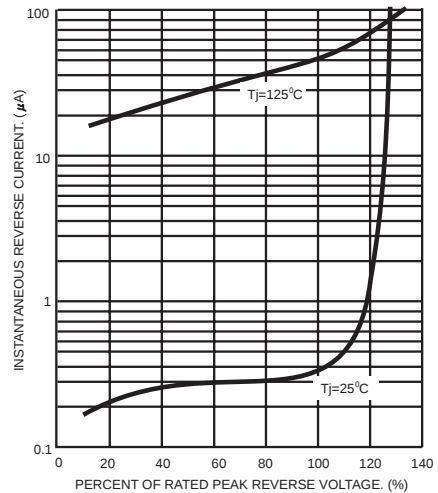


FIG.3- MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

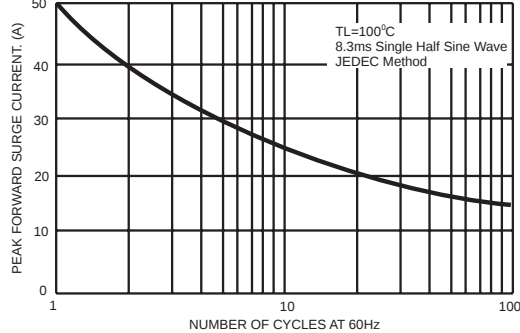


FIG.5- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

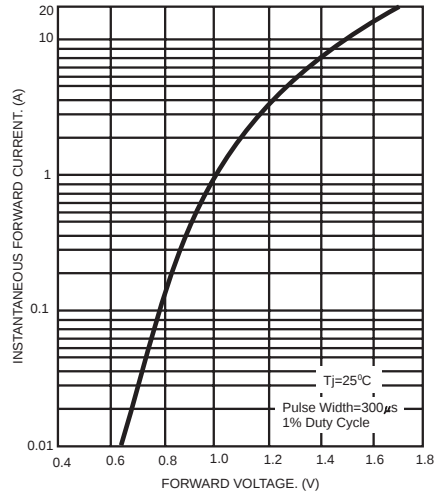


FIG.4- TYPICAL JUNCTION CAPACITANCE

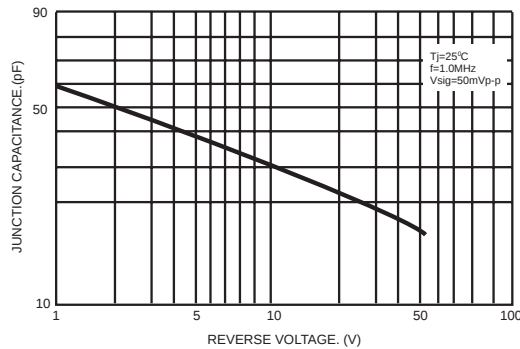
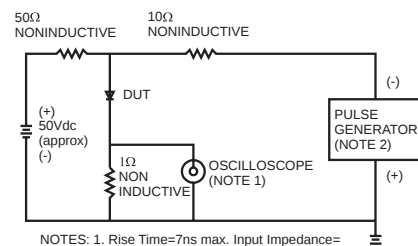


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



NOTES: 1. Rise Time=7ns max. Input Impedance=1 megohm 22pF
2. Rise Time=10ns max. Source Impedance=50 ohms

